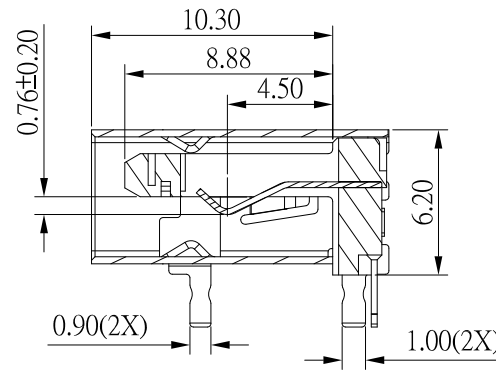
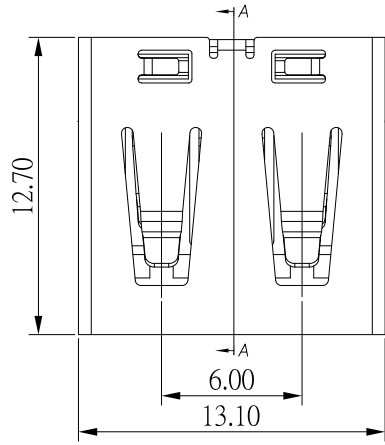


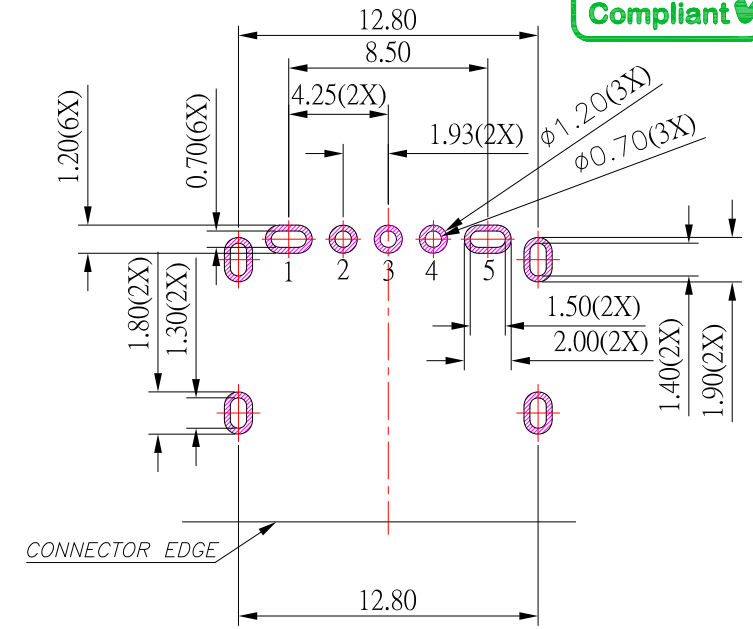


SUA-110H46-xx-S277

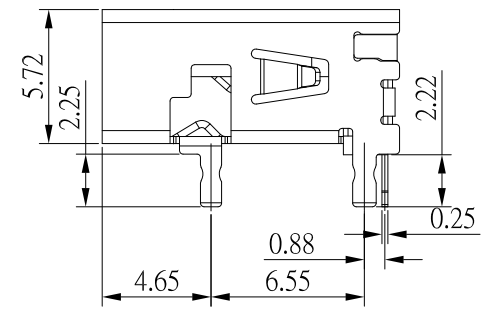
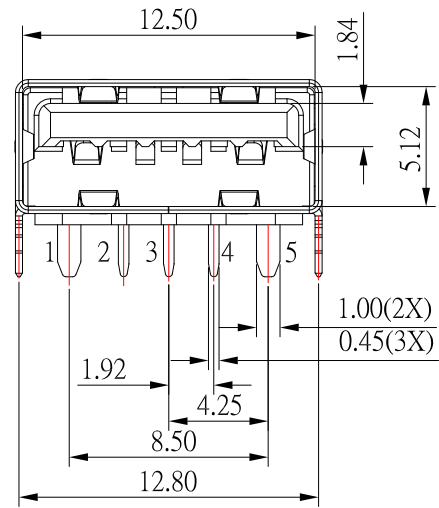
鍍層厚度 :	Color :
Blank : 1u"	Black : B
2 : 15u"	Green : GR
3 : 30u"	



SECTION: A-A



RECOMMENDED PCB LAYOUT



NOTE:

- 1.MATERIAL:
 - 1.1 Housing: PA10T
 - 1.2 Contact: Copper Alloy
 - 1.3 Shell: SUS
- 2.Finish:
 - 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
 - 3.1 Current Rate: 5.0 A(VBUS & GND)
 - 3.2 insulator Resistance:100MΩ Min
 - 3.3 Dielectric Strength: 100V AC
 - 3.4 Contact Resistance: 30mΩ Max
 - 3.5 Operation Temperature: -25°C ~ +85°C
 - 3.6 Insertion Force: 3.57 kgf Max
 - 3.7 Extraction Force: 1.02 kgf Min

4	更新圖面	Jack	052620
3	更新為A0版	Jack	101817
2	新增顏色編碼	Jack	100317
1	新增pin編號及圖示	Jack	092217
ITEM NO.	DESCRIPTION	DRAWN	DATE

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	05/26/20		MODLE	USB AF 2.0 90度 DIP 5PIN 直腳 無捲邊
CHECKED BY:	DATE	FINISH	DWG NO.	SUA-110H46-xx-S277
Jacky Chen	05/26/20	SCALE 1 : 1	PART NO.	SUA-110H46-xx-S277
APPROVED BY:	DATE	SHEET NO.	1 of 1	SIZE A4 VER R4
Tony Kao	05/26/20			